

MOSFET - Power, Single N-Channel, SUPERFET®, FAST, TOLL-4L

600 V, 150 mΩ, 19 A

NTBL150N60S5H

Description

The SUPERFET V MOSFET FAST series helps maximize system efficiency by the extremely low switching losses in hard switching application. The TOLL package offers improved thermal performance and excellent switching performance by providing a Kelvin Source configuration and lower parasitic source inductance.

Features

- 650 V @ $T_J = 150$ °C, Typ. $R_{DS(on)} = 120 \text{ m}\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free / BFR Free and are RoHS Compliant

Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

ABSOLUTE MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

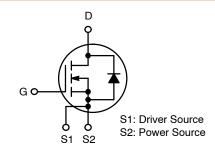
Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V _{DSS}	600	V
Gate-to-Source Voltage	DC	V _{GS}	±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	T _C = 25°C	I _D	19	Α
	T _C = 100°C		12	
Power Dissipation	T _C = 25°C	P_{D}	133	W
Pulsed Drain Current (Note 1)	T _C = 25°C	I _{DM}	67	Α
Pulsed Source Current (Body Diode) (Note 1)		I _{SM}	67	Α
Operating Junction and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C
Source Current (Body Diode)		I _S	19	Α
Single Pulse Avalanche Energy	$I_L = 4.1 \text{ A}$ $R_G = 25 \Omega$	E _{AS}	153	mJ
Avalanche Current		I _{AS}	4.1	Α
Repetitive Avalanche Energy (Note 1)		E _{AR}	1.33	mJ
MOSFET dv/dt		dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)			20	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. $I_{SD} \le 9.5 \text{ A}$, di/dt $\le 200 \text{ A/s}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
600 V	150 mΩ @ 10 V	19 A

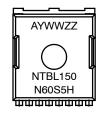


N-Channel MOSFET



H-PSOF8L 9.90x11.68, 1.20P CASE 100DC

MARKING DIAGRAM



A = Assembly Location Y = Year

WW = Work Week
ZZ = Assembly Lot Code
NTBL150N60S5H = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NTBL150N60S5H	H-PSOF8L	2000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	0.94	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	43	

ELECTRICAL CHARACTERISTICS (T_{.I} = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•		•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 10 mA, T_J = 25°C	600	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_J}$	I _D = 10 mA, Referenced to 25°C	-	630	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 600 V, T _J = 25°C	-	_	1	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
ON CHARACTERISTICS						
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 10 V, I_{D} = 9.5 A, T_{J} = 25°C	-	120	150	mΩ
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}, I_D = 1.8 \text{mA}, T_J = 25^{\circ}\text{C}$	2.7	_	4.3	V
Forward Trans-conductance	9FS	V _{DS} = 20 V, I _D = 9.5 A	_	18.3	_	S
CHARGES, CAPACITANCES & GATE	RESISTANCE					
Input Capacitance	C _{ISS}	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$	-	1713	-	pF
Output Capacitance	C _{OSS}		-	26.8	-	
Time Related Output Capacitance	C _{OSS(tr)}	I_D = Constant, V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	415	-	
Energy Related Output Capacitance	C _{OSS(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	44.8	-	
Total Gate Charge	Q _{G(TOT)}	V _{DD} = 400 V, I _D = 9.5 A, V _{GS} = 9.5 V	-	29.8	-	nC
Gate-to-Source Charge	Q_{GS}		-	8.38	-	
Gate-to-Drain Charge	Q_{GD}		_	8.34	-	
Gate Resistance	R_{G}	f = 1 MHz	-	1.05	-	Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	17.4	-	ns
Rise Time	t _r	$I_D = 9.5 \text{ A}, R_G = 10 \Omega$	-	5.14	-	
Turn-Off Delay Time	t _{d(OFF)}		_	54.9	-	
Fall Time	t _f		_	2.83	_	
SOURCE-TO-DRAIN DIODE CHARAC	CTERISTICS					
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_{SD} = 9.5 \text{ A}, T_{J} = 25^{\circ}\text{C}$	_	_	1.2	V
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, I _{SD} = 9.5 A,	-	319	-	ns
Reverse Recovery Charge	Q_{RR}	dl/dt = 100 A/μs, V _{DD} = 400 V	_	3999	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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TYPICAL CHARACTERISTICS

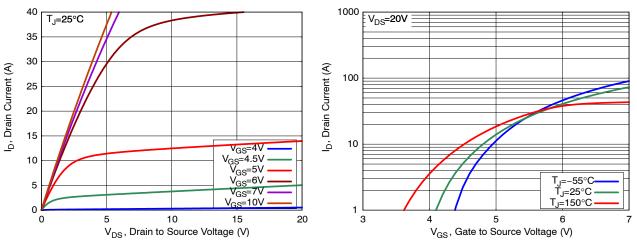


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

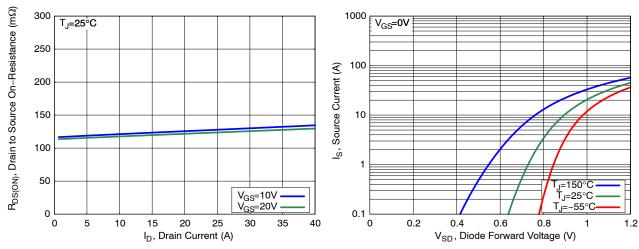


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage

Figure 4. Diode Forward Voltage vs. Source Current

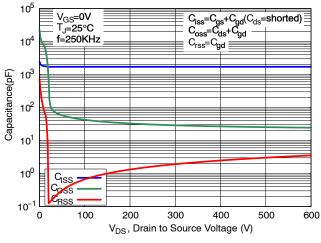


Figure 5. Capacitance Characteristics

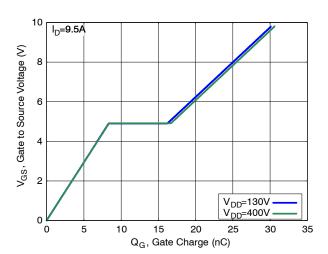


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS

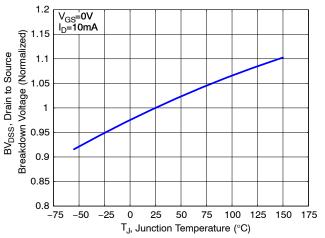


Figure 7. Breakdown Voltage Variation vs.
Temperature

T_C=25°C T_J=150°C

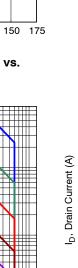
I_D, Drain Current (A)

10¹

10⁻¹ — 0.1

Single Pulse

Limited by R_{DS(ON)}



1000

Figure 9. Maximum Safe Operating Area

10

V_{DS}, Drain to Source Voltage (V)

100

pulseDuration=10u pulseDuration=100u pulseDuration=1m

pulseDuration=10m pulseDuration=DC

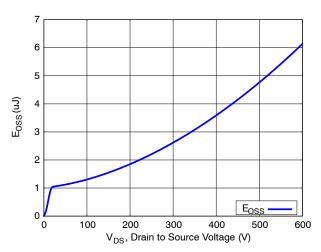


Figure 11. Eoss vs. Drain-to-Source Voltage

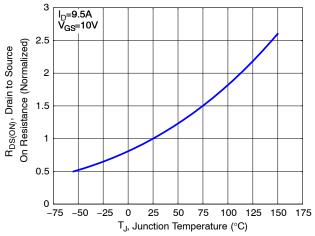


Figure 8. On–Resistance Variation vs.
Temperature

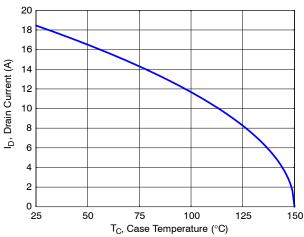


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL CHARACTERISTICS

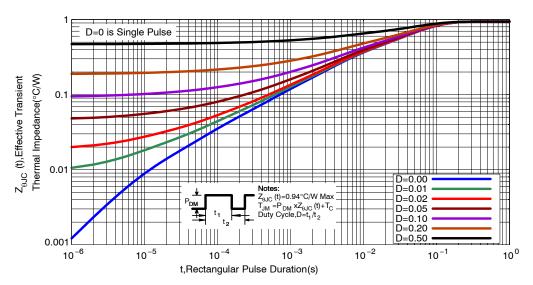
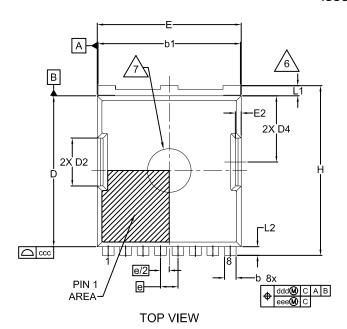
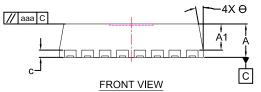


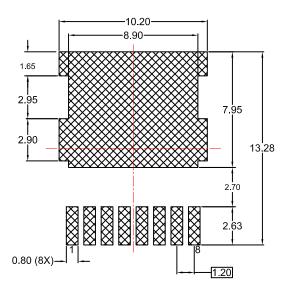
Figure 12. Transient Thermal Impedance

PACKAGE DIMENSIONS

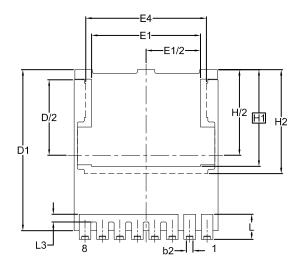
H-PSOF8L 9.90x11.68, 1.20P CASE 100DC ISSUE O







RECOMMENDED LAND PATTERN



BOTTOM VIEW

NOTES:

М	1		
MIN.	NOM.	MAX.	į
2.20	2.30	2.40	2
1.70	1.80	1.90	3
0.70	0.80	0.90	F
9.70	9.80	9.90	4 N
0.35	0.45	0.55	l "
0.40	0.50	0.60	_
10.28	10.38	10.48	
10.98	11.08	11.18	
3.20	3.30	3.40	
5.09	5.19	5.29	
4.45	4.55	4.65	
9.80	9.90	10.00	
7.40	7.50	7.60	
0.30	0.40	0.50	
8.20	8.30	8.40	
1.20 BSC			
11.58	11.68	11.78	
	MIN. 2.20 1.70 0.70 9.70 0.35 0.40 10.28 10.98 3.20 5.09 4.45 9.80 7.40 0.30 8.20	MIN. NOM. 2.20 2.30 1.70 1.80 0.70 0.80 9.70 9.80 0.35 0.45 0.40 0.50 10.28 10.38 10.98 11.08 3.20 3.30 5.09 5.19 4.45 4.55 9.80 9.90 7.40 7.50 0.30 0.40 8.20 8.30 1.20 BSC	2.20 2.30 2.40 1.70 1.80 1.90 0.70 0.80 0.90 9.70 9.80 9.90 0.35 0.45 0.55 0.40 0.50 0.60 10.28 10.38 10.48 10.98 11.08 11.18 3.20 3.30 3.40 5.09 5.19 5.29 4.45 4.55 4.65 9.80 9.90 10.00 7.40 7.50 7.60 0.30 0.40 0.50 8.20 8.30 8.40 1.20 BSC

6.66 BSC

5.89

0.70

0.60

0.53

10° REF

0.20

0.20

0.25

0.20

5.99

1.83

0.80

0.70

0.63

5.79

1.63

0.60

0.50

0.43

H1 H2 H/2

L1

L2

L3

Θ aaa

ccc

ddd eee

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